Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	14	salient adj electrode near10 (gold or au) and lead near10 (gold or au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 09:44
L2	4524	electrode near10 (gold or au) and lead near10 (gold or au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 09:44
L3	1914	electrode near4 (gold or au) and lead near4 (gold or au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 09:45
L4	16	external adj electrode near4 (gold or au) and lead near4 (gold or au)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 09:45
S1	2	"6699737".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 12:20
S2	7	("20010019852" "20010029062" "20020013014" "20020037605" "20020058358" "6444492" "6475877").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/31 07:40
S3	708	chip and electrode and wir\$4 adj (wafer or substrate) and thin adj film and leads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 10:54
54	9	chip and salient adj electrode and wir\$4 adj (wafer or substrate) and thin adj film and leads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 07:08

S 5	362	chip and electrode and wir\$4 adj (wafer or substrate) and thin adj film and leads and pitch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:04
S6	78	chip and electrode and wir\$4 adj (wafer or substrate) and thin adj film and leads and pitch and jig	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:36
S7	385	438/119.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:13
S8	3	chip and salient adj electrode and wir\$4 adj (wafer or substrate) and thin adj film and leads and pitch and jig	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:23
S9	3	(chip and electrode and wir\$4 adj (wafer or substrate) and thin adj film and leads and pitch and jig). clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:23
S12	2756	438/612.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:29
S13	1553	438/613.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:29
S14	416	438/686.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:29

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S15	9471	renesas.as. and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:37
S16	1779	renesas.as. and semiconductor adj chip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:37
S17	678	renesas.as. and semiconductor adj chip and electrode and wir\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:40
S18	32	renesas.as. and semiconductor adj chip and electrode and wir\$4 and jig	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/31 11:41
S19	1161	438/125.CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 11:13
S20	314	438/611.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 11:13
S21	7	("20010019852" "20010029062" "20020013014" "20020037605" "20020058358" "6444492" "6475877").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 11:21
S22	4	(("6444492") or ("6475877")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 11:36

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S23	9	chip and salient adj electrode and wir\$4 and bond\$4 and leads and thin adj film and pitch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 11:31
S24	1	09/150693.app.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 11:31
S25	7	chip and salient adj electrode and wir\$4 adj (wafer or substrate) and thin adj film and leads and pitch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 07:28
S26	7	chip and salient adj electrode and wir\$4 adj (wafer or substrate) and thin adj film and leads and pitch and bond\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 07:35
S27		"20010002066" and pitch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 09:42
S28	2	"20040142512" and pitch	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 07:43
S29	2	"20040142512" and pitch near7 smaller	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 08:03
S30	2	"20040142512" and pitch near7 smaller and salient adj electrode	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/02 08:04